

Advansic Pulse Heat Tools

Features

- The heat tool for semiconductor bonding process.
- Excellent thermal response and uniformity by generating the heat from the SiC ceramic itself.
- The heat reaches at the max rate of 200C/sec.
- Enable to achieve pulse heating with the minimum of 500W electric power.
(Only for the operation of 12 x 12mm heat tool without attachment)
- The available sizes are: 12 x 12 mm, 22 x 22 mm, 35 x 35 mm

Production code	Size	Recommended object size	max. temperature	max. heat rate	Cooling time	Temperature uniformity
PHT-12	12 × 12mm	~7mm	450°C	200°C/sec	2.4sec*1	±6°C (450°C, within 5mm□)
PHT-22	22 × 22mm	~15mm	450°C	200°C/sec	4.7sec*1	±5°C (450°C, within 5mm□)
PHT-35	35 × 35mm	15~25mm	450°C	150°C/sec	7.6sec*1	±9°C (450°C, within 5mm□)

Without attachment (Heat tool only), Apply only internal cooling line 0.5MPa – 1 source.

22 x 22mm Pulse Heat Tool PHT-22

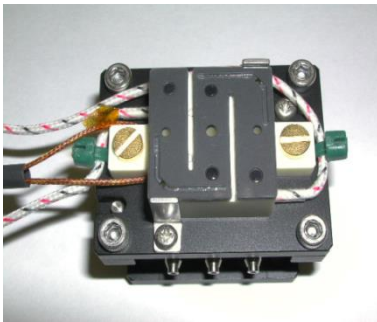


Fig.1 Appearance

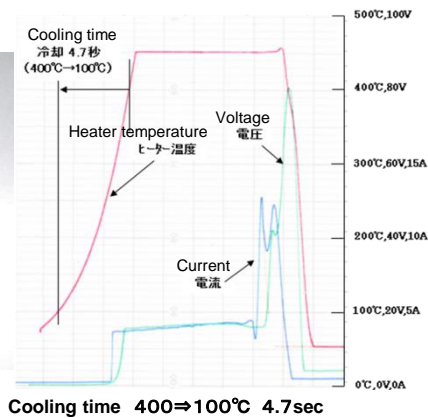
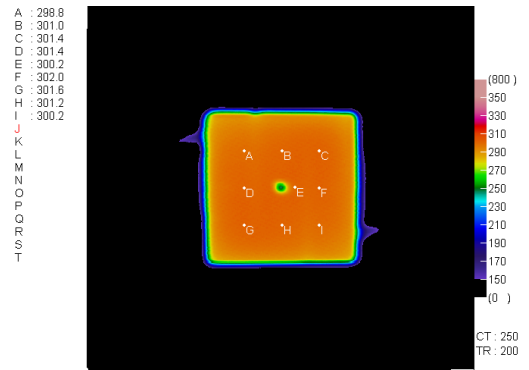


Fig.2 Time chart of heater performance (Heat tool only)



ΔT=3.2°C (±1.6°C) ; within 12mm

Fig.3 Temperature uniformity on the attachment (measured by infrared thermometer)